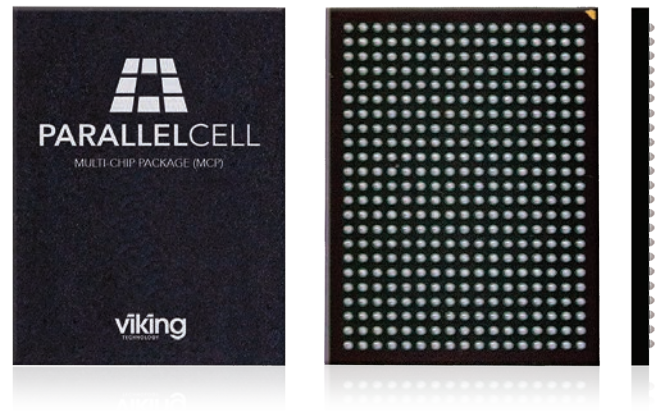


PRODUCT BRIEF | MCP

PARALLELCELL MULTI-CHIP PACKAGE (MCP)

Ultra High Density Memory Solution for Military & Embedded Applications

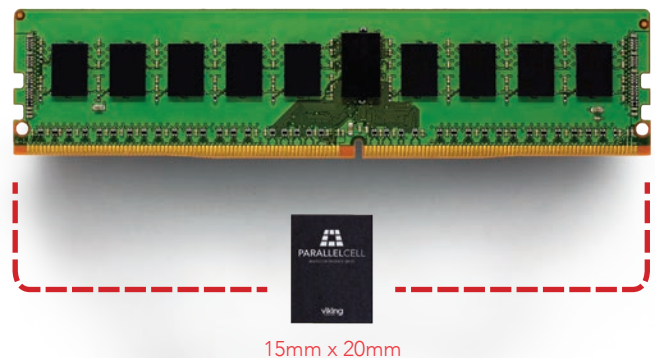
Viking Technology ParallelCell Multi-Chip Package (MCP) is part of the extreme density line of DDR4 memory products optimized for the embedded, industrial, and military/aerospace markets. ParallelCell products achieve significantly higher memory performance and density per cubic inch than conventional memory DIMMs. These performance and density milestones will critically change the way future system hardware is designed and deployed.



BENEFITS

Very small footprint: Saves up to 85% board space vs. Standard DIMM Modules	Very high memory capacity per cu. in.	Very high memory bandwidth per cu. in.
Rugged: Soldered-down – No DIMM connector	Superior signal integrity	Lower cost motherboard due to easier DDR routing

SPEEDS		VOLTAGE
DDR4	2400/2667	1.2V
TEMPERATURE		
Industrial	-40°C to 95°C	
Extended	-40°C to 105°C	
Military	-55°C to 125°C	
Commercial	0°C to 70°C	



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